BOMcheck.net

Full Material Declaration for attached parts list

Report generated: 04 July 2023, 09:25 GMT

Diotec Semiconductor

Diotec Semiconductor AG

DUNS number: 330866844
-, Kreuzmattenstr. 4, Heitersheim, 79423, Germany
Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: [Approved on 04 July 2023, 09:24 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	1.1%	Nickel REACH Article 67 Exemption	7440-02-0	1%
			Gold	7440-57-5	11.5%
			Polydimethylsiloxane rubber	63394-02-5	25%
			Silicon	7440-21-3	62.5%
Die attach	Lead and Lead alloys	4%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	61.7%	Carbon black	1333-86-4	0.3%
			Epoxy resin 89	26335-32-0	28.3%
			Quartz sand	60676-86-0	71.4%
Leadfinish	Tin plating	1%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	32.2%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
KBP_P73	KBP_P73	1.5	g